

ABSTRACT OF THE DISCLOSURE

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To inspect a finer device pattern formed in a semiconductor wafer, there is provided an inspection equipment including means for supporting a semiconductor wafer as a specimen and moving it to a predetermined position of inspection, means for projecting an ultraviolet light onto the specimen supported on the specimen supporting means, an ultraviolet imaging means for detecting a reflected light or transmitted light from the specimen illuminated by the ultraviolet light projecting means and picking up an image of the specimen, means for processing the image picked up by the ultraviolet imaging means. The image picked up by the imaging means is processed and analyzed by the image processing means to inspect the specimen.